

Description

The HPHB32N06LT118 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =30 A

 $R_{DS(ON)} < 26m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

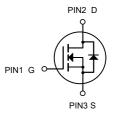
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Product ID	Pack	Brand	Qty(PCS)
HPHB32N06LT118	TO-252-2L(DPAK)	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	A	
ID@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А	
Ідм	Pulsed Drain Current ²	46		
EAS	Single Pulse Avalanche Energy ³	25.5	mJ	
las	Avalanche Current	22.6	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W	
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
Reja	Thermal Resistance Junction-Ambient ¹	62	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	3.6	°C/W	



(DPAK)



N-Channel MOSFET

N-Channel Enhancement Mode MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	eter Conditions		Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
∆BV _{DSS} /∆T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.063		V/°C
		V _{GS} =10V , I _D =15A		22	26	
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		30	38	mΩ
VGS(th)	Gate Threshold Voltage		1.2		2.5	V
$\bigtriangleup V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.24		mV/°C
		V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	_
ldss	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA
lgss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		17		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.2		Ω
Qg	Total Gate Charge (4.5V)			12.6		
Qgs	Gate-Source Charge			3.2		nC
Q_{gd}	Gate-Drain Charge	-		6.3		
Td(on)	Turn-On Delay Time			8		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		14.2		
Td(off)	Turn-Off Delay Time	—R _G =3.3 , I _D =10A		24.4		ns
T _f	Fall Time			4.6		
Ciss	Input Capacitance			1378		
Coss	Output Capacitance			86		pF
Crss	Reverse Transfer Capacitance			64		
ls	Continuous Source Current ^{1,5}				23	Α
Іѕм	Pulsed Source Current ^{2,5}	−V _G =V _D =0V , Force Current			46	A
Vsd	Diode Forward Voltage ²	V _{GS} =0V , Is=1A , T _J =25°C			1.2	V

Note :

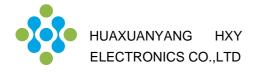
1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$

3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A

4.The power dissipation is limited by 150°C junction temperature

5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



HPHB32N06LT118 N-Channel Enhancement Mode MOSFET

Typical Characteristics

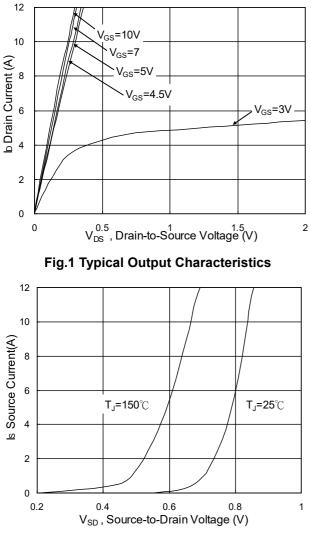


Fig.3 Forward Characteristics of Reverse

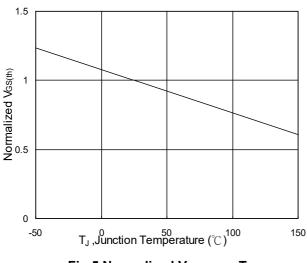


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

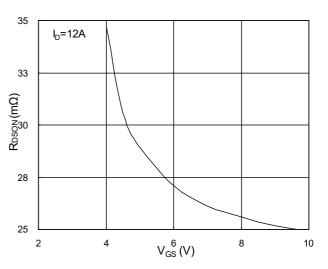


Fig.2 On-Resistance v.s Gate-Source

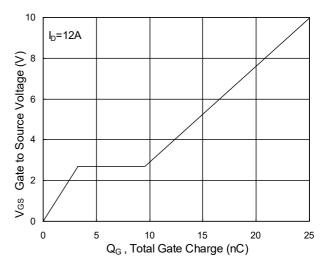


Fig.4 Gate-Charge Characteristics

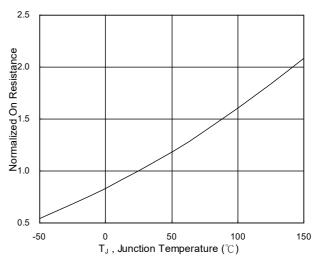
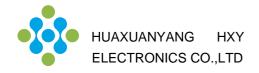


Fig.6 Normalized R_{DSON} v.s T_J



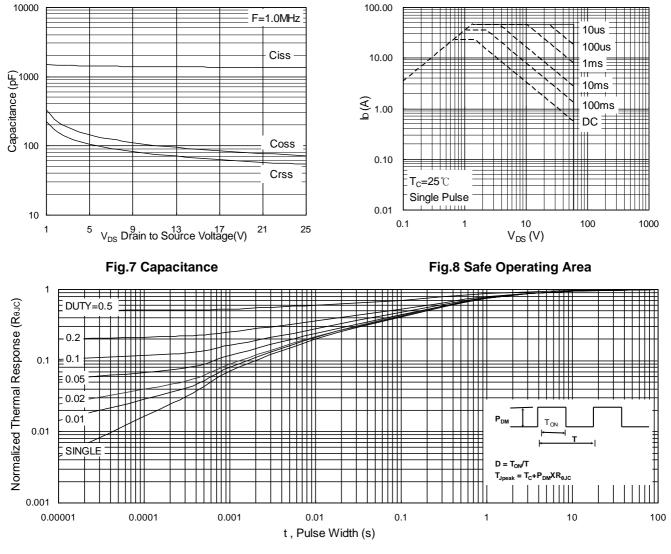


Fig.9 Normalized Maximum Transient Thermal Impedance

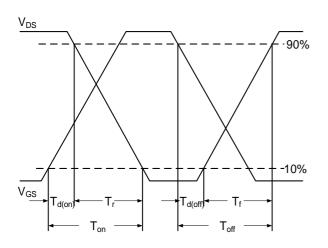
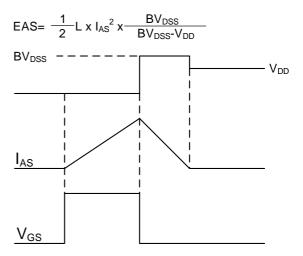
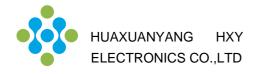


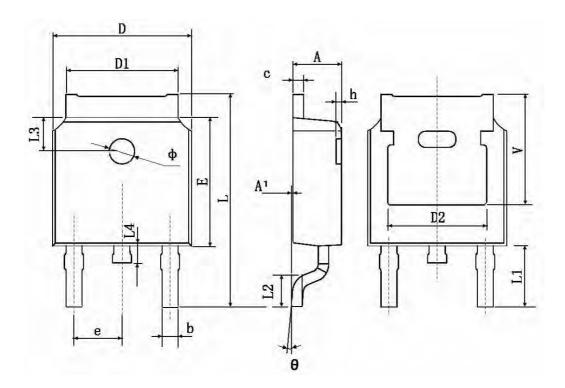
Fig.10 Switching Time Waveform







TO-252-2L(DPAK) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0 °	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP. 0.211 TYP.		1 TYP.		



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